

220040US-902-236424-2-PCT

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
CLAUDE JAUSSAUD ET AL. : ATTN: APPLICATION DIVISION
SERIAL NO: NEW U.S. PCT APPLN :
(Based on PCT/FR00/02468)
FILED: HEREWITH :
FOR: CREATION OF AN ELECTRICALLY:
CONDUCTING BONDING BETWEEN
TWO SEMI-CONDUCTOR ELEMENTS

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Prior to a first examination on the merits, please amend the above-identified
application as follows:

IN THE CLAIMS

Please cancel Claims 1-10 without prejudice.

Please add new Claims 11-20 as follows:

11. (New) Method of creating an electrically conducting bonding between a face of
a first semiconductor element and a face of a second semiconductor element by heat
treatment, comprising:

depositing at least one layer of material on said face of the first semiconductor
element and at least one layer of material on said face of the second semiconductor element,